



DATE: 9 June, 2017

PCN #: 2153

PCN Title: Qualification of Additional Assembly Sites and Package Outline Dimension Changes

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request within 30 days as well. Otherwise, samples may not be built prior to this change. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



**PRODUCT CHANGE NOTICE**

**PCN-2153 REV 1**

<b>Notification Date:</b>	<b>Implementation Date:</b>	<b>Product Family:</b>	<b>Change Type:</b>	<b>PCN #:</b>
9 June, 2017	9 September, 2017	Discrete	Assembly Site and Design	<b>2153</b>
<b>TITLE</b>				
Qualification of Additional Assembly Sites, and Package Outline Dimension Changes				
<b>DESCRIPTION OF CHANGE</b>				
<p>This PCN is being issued to notify customers that in order to assure continuity of supply for select parts, Diodes has qualified additional assembly and test sites, Tianshui Huatian Electronic Group (HTME) using wire bond and Eris Technology Corp (ERIS) using clip bond for specific devices. For select parts using the TO252 package, the Package Outline Dimensions (POD) will change for one of the dimensions.</p> <p>Full electrical characterization and high reliability testing has been completed on representative part numbers to ensure there is no change to device functionality or electrical specifications in the datasheet.</p> <p>Please contact your local Diodes representatives for any questions or additional information.</p>				
<b>IMPACT</b>				
<p>Figure 1: Current Configuration of TO220AB Figure 2: New Configuration for TO220AB (Option A is baseline and Eris, Option B is HTME) Note: The new POD's dimensions are the same as the baseline.</p> <p>Figure 3: Current Configuration of TO252 Figure 4: New Configuration of TO252 (Option A is baseline and Option B is HTME) Note: The L4 dimension has changed from min 0.64mm to min 0.60mm</p> <p>Figure 5: Current Configuration of TO263 Figure 6: New Configuration of TO263AB (Option A is baseline and Option B is HTME) Note: The new POD's dimensions are the same as the baseline.</p>				
<b>PRODUCTS AFFECTED</b>				
<p>Table 1: Additional Assembly and Test Site, Tianshui Huatian Electronic Group in Tianshui, China (HTME) Table 2: Additional Assembly and Test Site, Eris Technology Corp in New Taipei, Taiwan (ERIS) Table 3: Additional Assembly and Test Sites, HTME and ERIS</p>				
<b>WEB LINKS</b>				
<b>Manufacturer's Notice:</b>	<a href="https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/">https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/</a>			
<b>For More Information Contact:</b>	<a href="http://www.diodes.com/contacts.html">http://www.diodes.com/contacts.html</a>			
<b>Data Sheet:</b>	<a href="http://www.diodes.com/catalog">http://www.diodes.com/catalog</a>			
<b>DISCLAIMER</b>				
<b>Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.</b>				

**Table 1: Additional Assembly and Test Site, Tianshui Huatian Electronic Group in Tianshui, China (HTME)**

SBR1045CTL-13	SBR10U200CTB-13-G	SBR20A120CT-G	SBR20U40CT-G	SBR30A45CTB-13-G	SBR5U100D1-13
SBR10100CT-G	SBR10U200CTB-G	SBR20A150CT-G	SBR20U60CT-G	SBR30A45CT-G	SBR6100CTL-13
SBR10100CTL-13	SBR10U300CT-G	SBR20A200CTB-13-G	SBR30150CT-G	SBR30A50CT-G	SBR6200CTL-13
SBR10120CTL-13	SBR10U45D1-13	SBR20A200CT-G	SBR30200CT-G	SBR30A60CTB-13-G	SBR660CTL-13
SBR10150CT-G	SBR15U100CTL-13	SBR20A300CT-G	SBR30300CT-G	SBR30A60CT-G	
SBR10150CTL-13	SBR20150CT-G	SBR20A40CT-G	SBR3045SCTB-13-G	SBR40100CT-G	
SBR10200CT-G	SBR2045CT-G	SBR20A60CTB-13-G	SBR30A100CTB-13-G	SBR40150CT-G	
SBR10200CTL-13	SBR2060CT-G	SBR20A60CT-G	SBR30A150CT-G	SBR4060CT-G	
SBR1045D1-13	SBR20A100CT-G	SBR20U150CT-G	SBR30A40CT-G	SBR545D1-13	

**Table 2: Additional assembly and test site Eris Technology Corp in New Taipei, Taiwan (ERIS)**

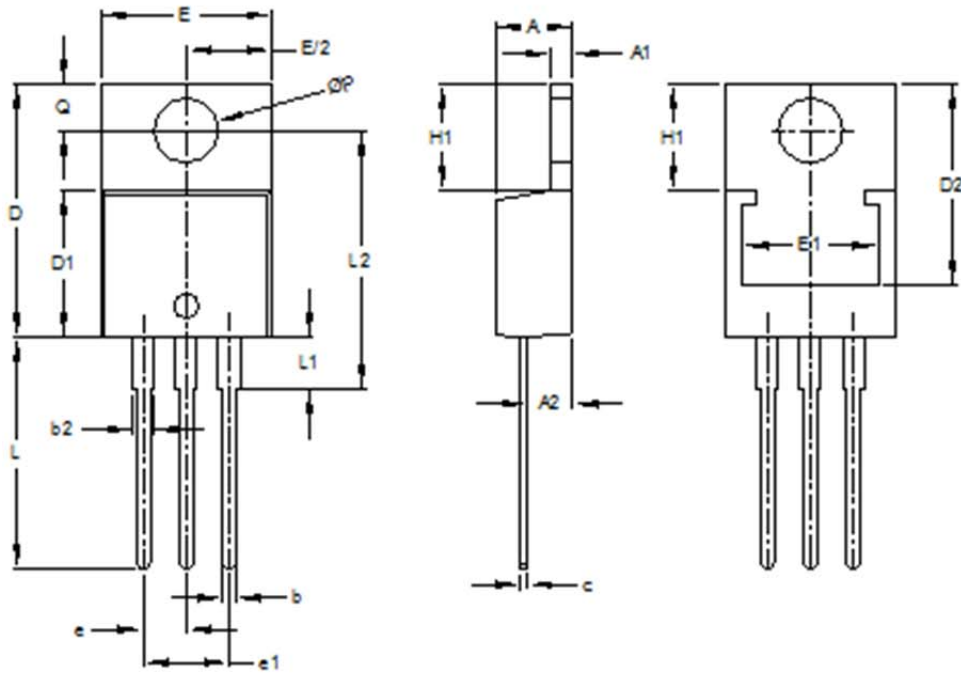
SBR40U100CT-G	SBR40U120CT-G	SBR60A100CT-G			
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**Table 3: Additional Test and Assembly Sites, HTME and Eris**

SBR10U100CT-G	SBR20100CT-G	SBR20A45CT-G	SBR20U100CT-G	SBR30100CT-G	SBR3045CT-G
SBR3060CT-G	SBR30A100CT-G	SBR30A120CT-G			

Figure 1: Current Configuration of TO220AB

TO220AB



TO220AB			
Dim	Min.	Max.	Typ.
A	3.56	4.82	-
A1	0.51	1.39	-
A2	2.04	2.92	-
b	0.39	1.01	0.81
b2	1.15	1.77	1.24
c	0.356	0.61	-
D	14.22	16.51	-
D1	8.39	9.01	-
D2	11.45	12.87	-
e	-	-	2.54
e1	-	-	5.08
E	9.66	10.66	-
E1	6.86	8.89	-
H1	5.85	6.85	-
L	12.70	14.73	-
L1	-	4.42	-
L2	15.80	17.51	16.00
P	3.54	4.08	-
Q	2.54	3.42	-
All Dimensions in mm			

Figure 2: New Configuration for TO220AB (Option A is baseline and Eris, Option B is HTME)

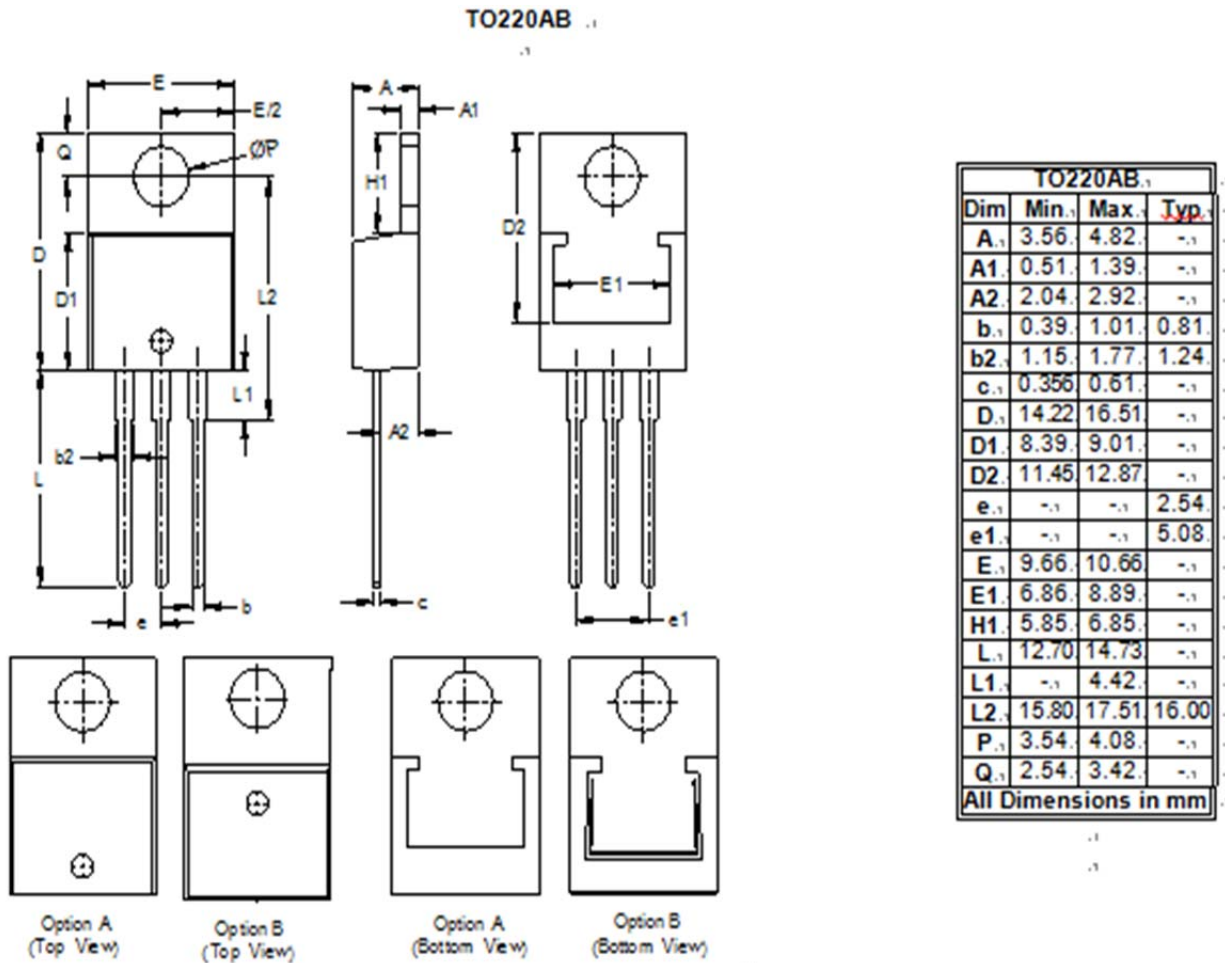
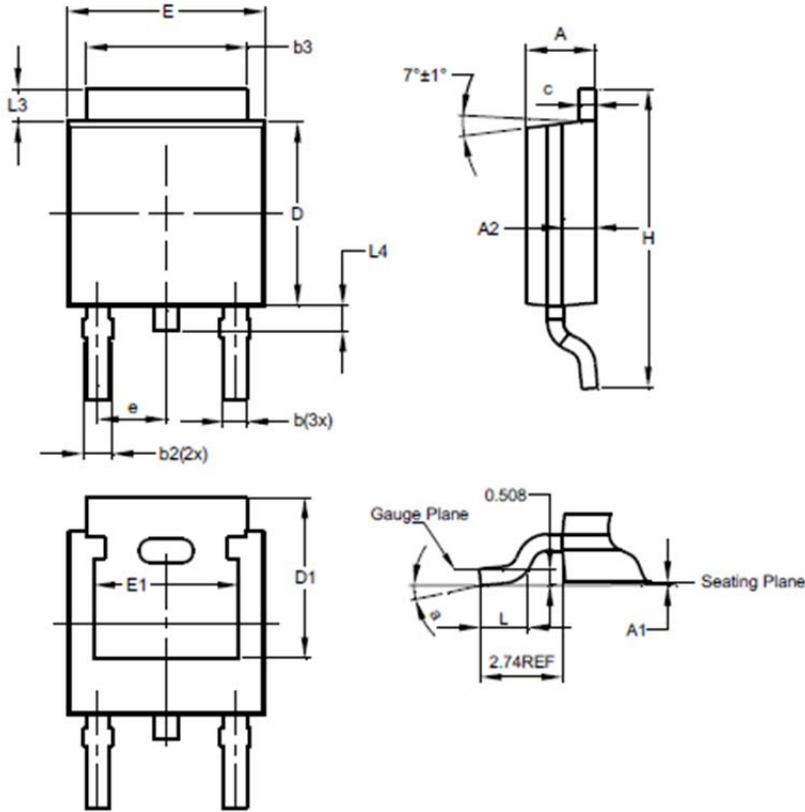


Figure 3: Current Configuration of TO252

TO252 (DPAK)



TO252 (DPAK)			
Dim	Min	Max	Typ
A	2.19	2.39	2.29
A1	0.00	0.13	0.08
A2	0.97	1.17	1.07
b	0.64	0.88	0.783
b2	0.76	1.14	0.95
b3	5.21	5.46	5.33
c	0.45	0.58	0.531
D	6.00	6.20	6.10
D1	5.21	-	-
e	-	-	2.286
E	6.45	6.70	6.58
E1	4.32	-	-
H	9.40	10.41	9.91
L	1.40	1.78	1.59
L3	0.88	1.27	1.08
L4	0.64	1.02	0.83
a	0°	10°	-
All Dimensions in mm			

Figure 4: New Configuration of TO252 (Option A is baseline and Option B is HTME)  
The L4 dimension has changed from min 0.64mm to min 0.60mm

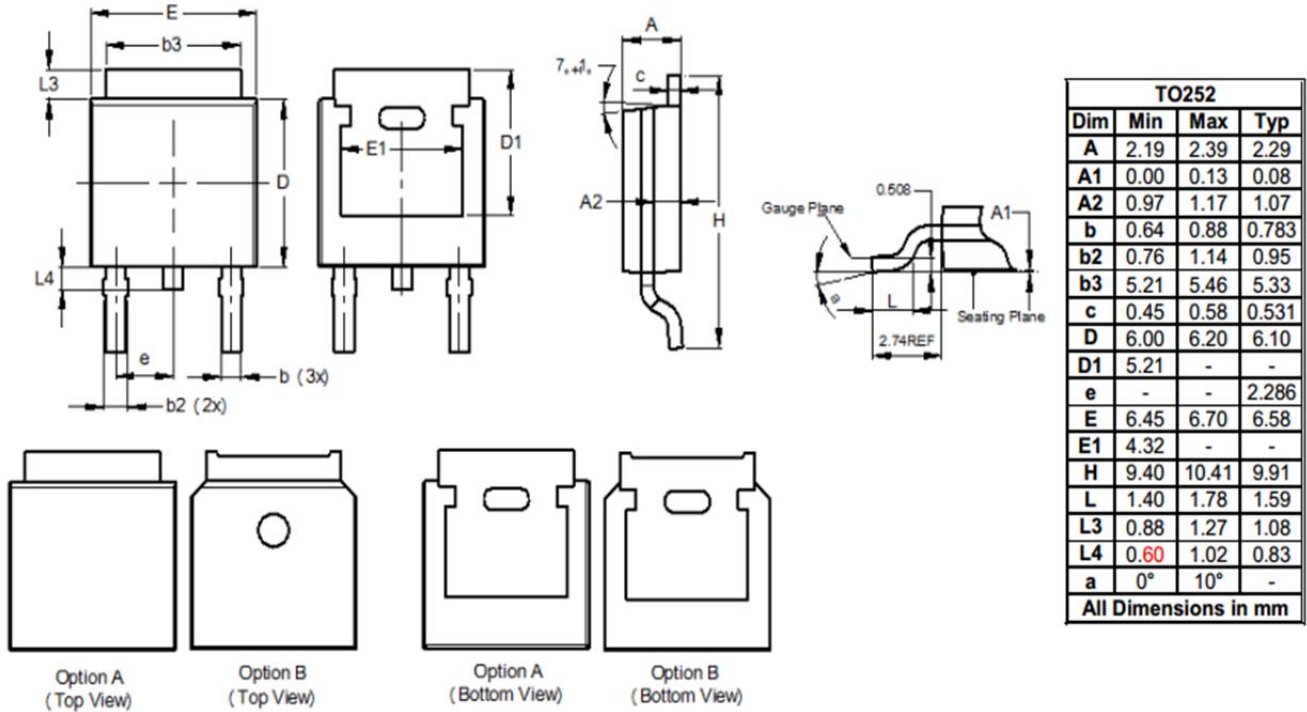
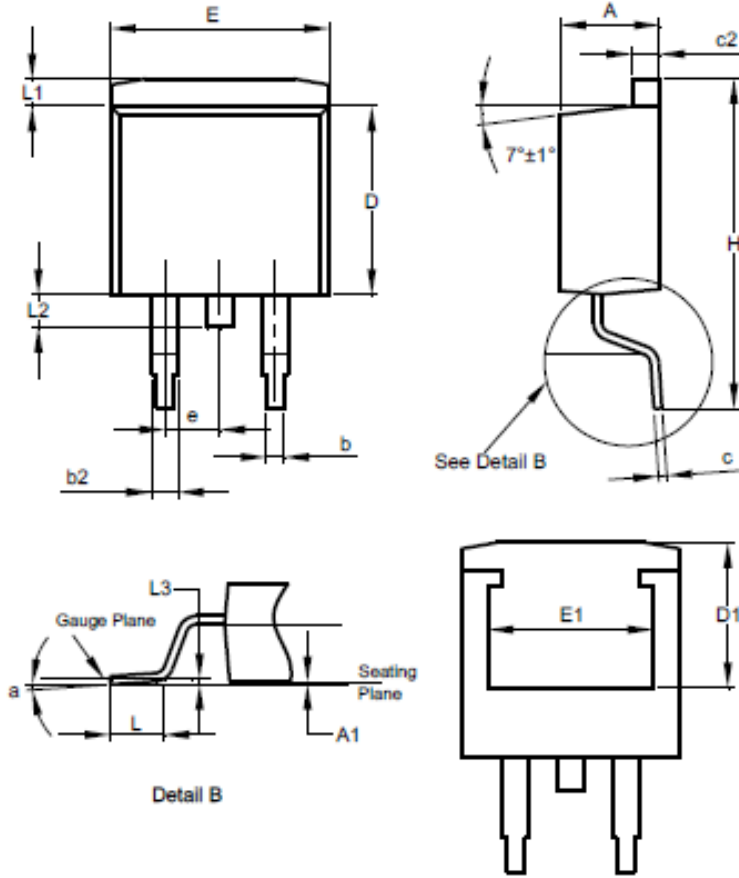


Figure 5: Current Configuration of TO263

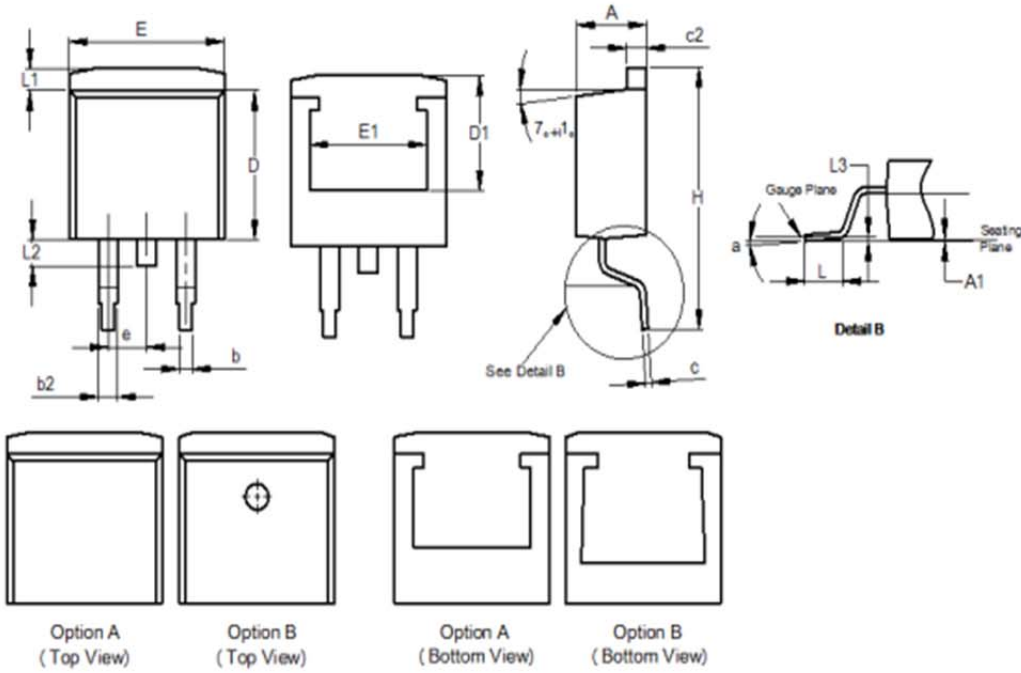
**TO263AB (D2PAK)**



TO263AB (D2PAK)			
Dim	Min	Max	Typ
A	4.07	4.82	-
A1	0.00	0.25	-
b	0.51	0.99	-
b2	1.15	1.77	-
c	0.356	0.73	-
c2	1.143	1.65	-
D	8.39	9.65	-
D1	6.55	6.95	-
e	2.54 TYP		
E	9.66	10.66	-
E1	6.23	8.23	-
H	14.61	15.87	-
L	1.78	2.79	-
L1	-	1.67	-
L2	-	1.77	-
L3	-	-	0.254
a	0°	8°	-
All Dimensions in mm			



Figure 6: New Configuration of TO263AB  
(Option A is baseline and Option B is HTME)



TO263AB			
Dim	Min	Max	Typ
A	4.07	4.82	-
A1	0.00	0.25	-
b	0.51	0.99	-
b2	1.15	1.77	-
c	0.356	0.73	-
c2	1.143	1.65	-
D	8.39	9.65	-
D1	6.55	6.95	-
e	2.54 TYP		-
E	9.66	10.66	-
E1	6.23	8.23	-
H	14.61	15.87	-
L	1.78	2.79	-
L1	-	1.67	-
L2	-	1.77	-
L3	-	-	0.254
a	0°	8°	-
<b>All Dimensions in mm</b>			